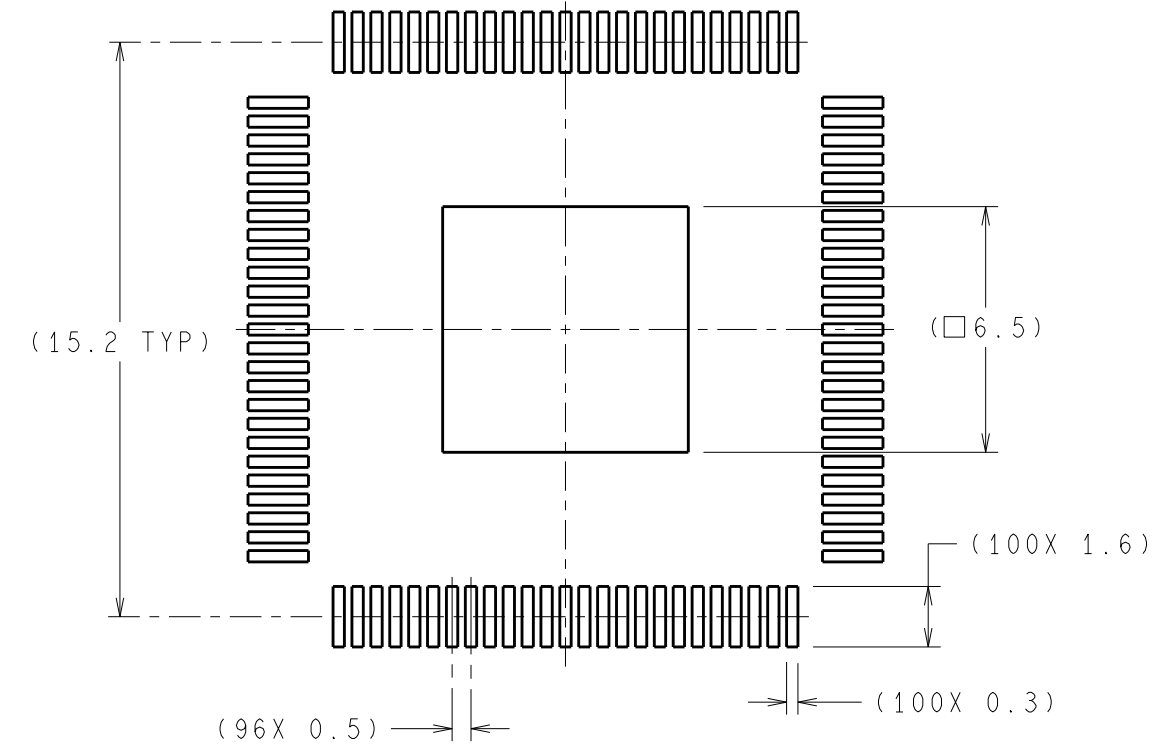
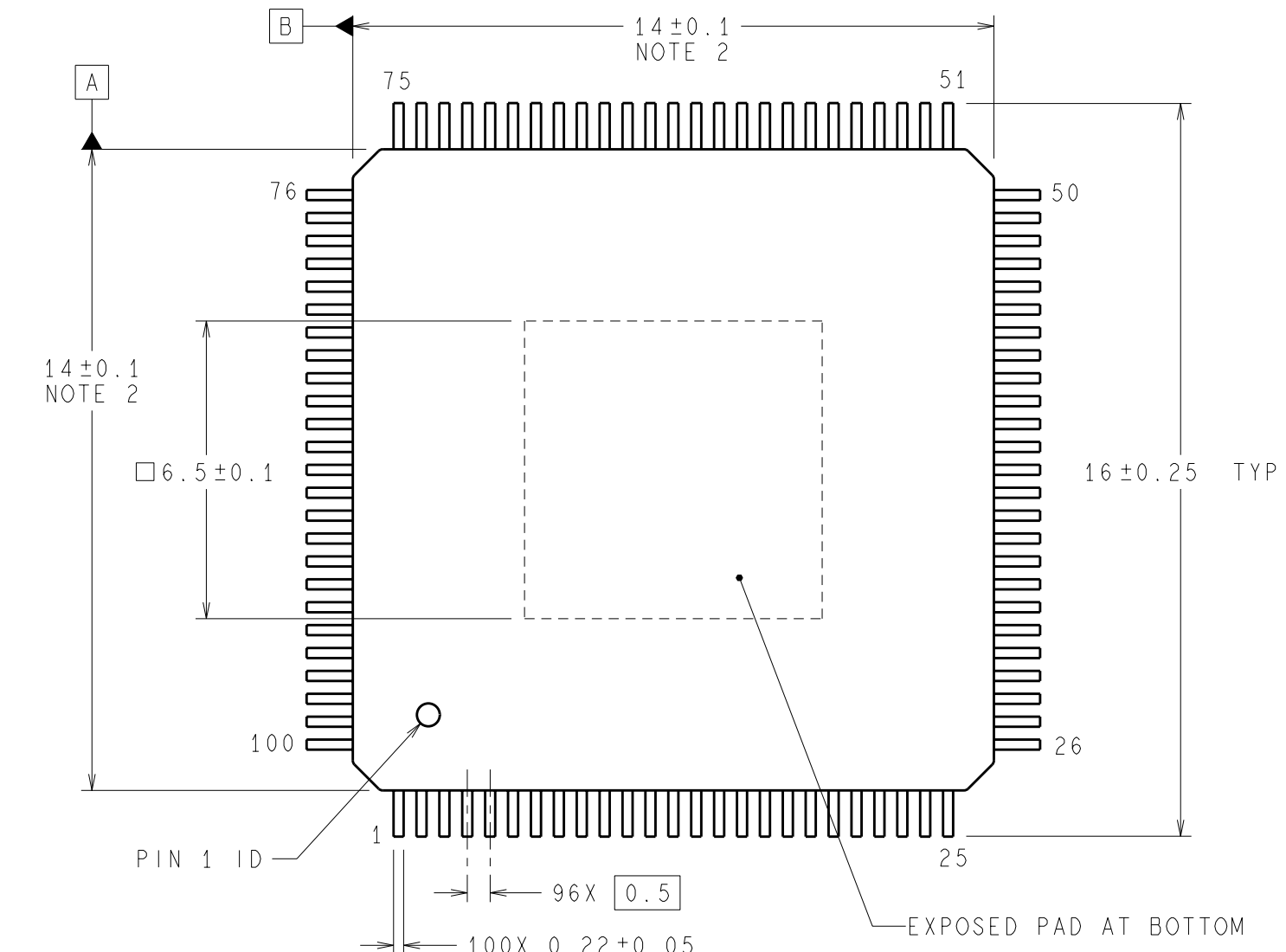
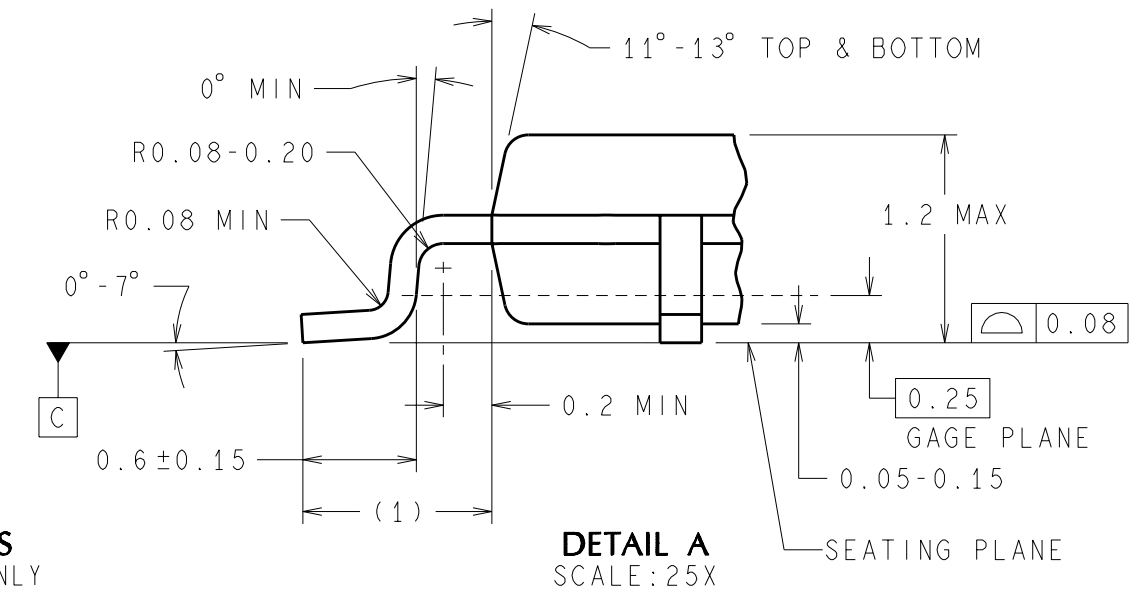


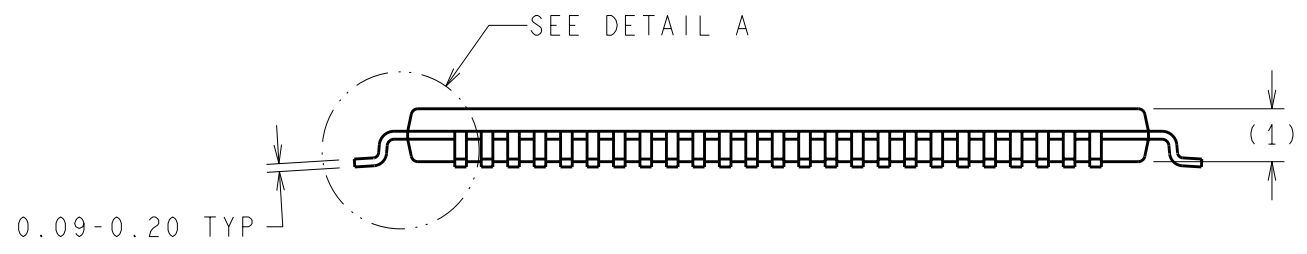
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	1828	06/02/2005	AS/MS/SN



RECOMMENDED LAND PATTERN



DETAIL A  
SCALE: 25X



DIMENSIONS ARE IN MILLIMETERS  
DIMENSION IN ( ) FOR REFERENCE ONLY

- NOTES: UNLESS OTHERWISE SPECIFIED
- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE ([www.national.com](http://www.national.com)).
  - DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
  - REFERENCE JEDEC REGISTRATION MS-026, VARIATION AED-HD.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090
DRAWN	ASNOR SULAIMAN	06/02/2005	
DFTG. CHK.	MARTA SUCHY	06/02/2005	
ENGR. CHK.	N. SANTHIRAN	06/02/2005	
TQFP, 14x14x1mm, 100 LEAD, 0.5mm PITCH, EXP PAD, 6.5x6.5mm			
PROJECTION	SCALE	SIZE	DRAWING NUMBER
 MM	NTS	B	(SC)MKT-VXF100B
FORMERLY: N/A			REV A
SHEET 1 of 1			